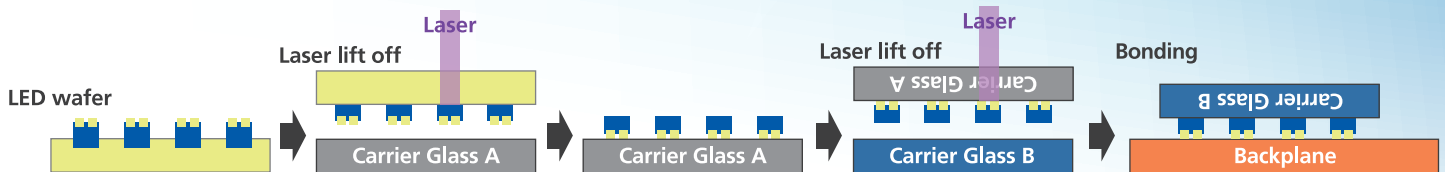


Carrier Glass Substrate Lineup for MicroLED

► 應用 Applications

- Carrier for Micro LED Display mass transfer process
Micro LED顯示器巨量轉移製程用載板
- In the manufacturing of Micro LEDs, carrier substrates are used multiple times during the process of transferring LED chips to the backplane.
在Micro LED製造過程中，於LED晶片轉移至背板 (Backplane) 的巨量轉移製程中，載板基板需被多次使用。



► 特點 Features

- 1 Wide Range of Glass Lineup : CTE variations
多樣化玻璃產品：提供不同熱膨脹係數規格選擇
- 2 FP-01UV glass : High UV transmittance
具備高UV透過率
- 3 Variety for size format and thickness
支援多樣化尺寸格式與厚度規格

► 技術資料 Technical Data

Glass Lineup

Property	Unit	Glass for Carrier				
		Glass A	Glass B	Glass C	Glass D	Glass E
CTE(50-350°C)	[10 ⁻⁶ -6/K] [ppm/°C]	3.8	5.0	6.0	7.2	9.2
Young's Modulus	[GPa]	85	76	76	80	72
Thickness availability	[mm]	0.4-0.5	0.7-1.8	0.7-1.8	0.7-1.8	0.3-1.8

FP-01UV glass

Transmittance @250nm (Reference value)	0.5t : ~85% 1.0t : ~80%
CTE [x10 ⁻⁶ /°C]	5.3
Young's modulus [GPa]	65

